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Understanding Embedded - FPGAs (Field Programmable Gate Array)

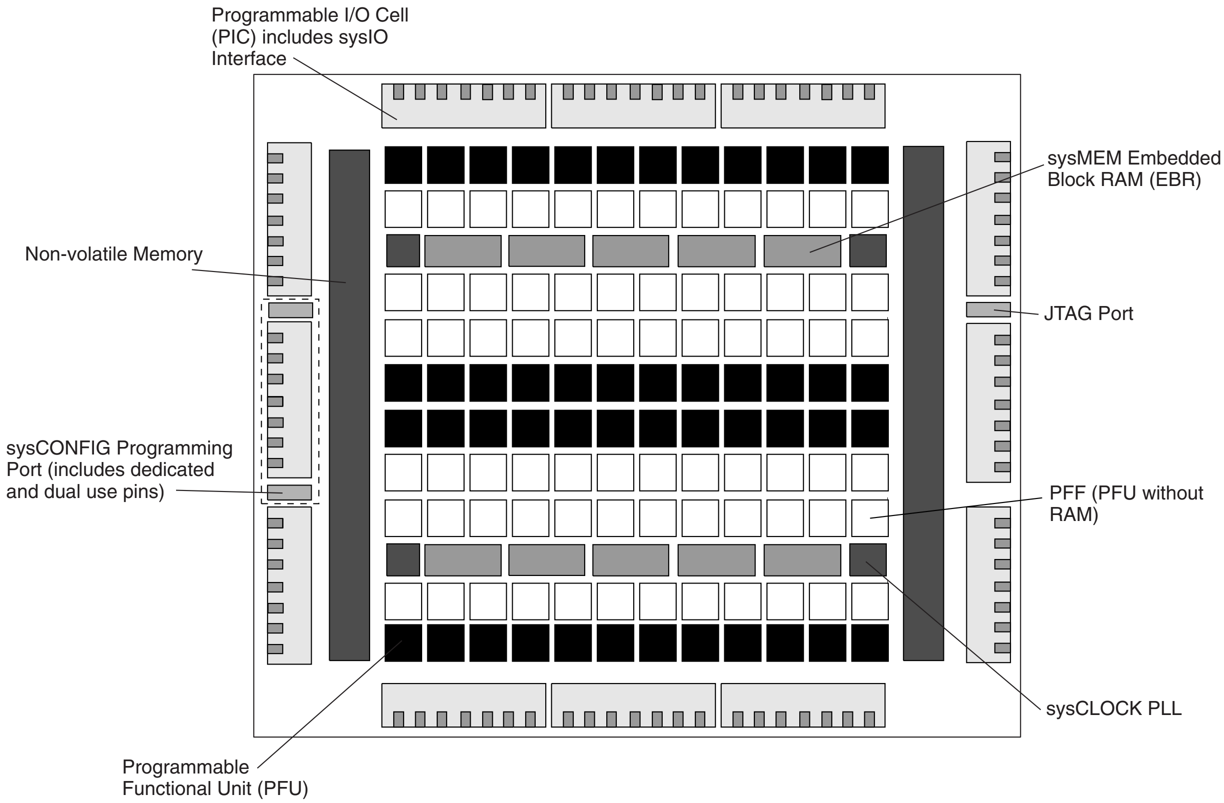
Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications,

Details	
Product Status	Obsolete
Number of LABs/CLBs	-
Number of Logic Elements/Cells	6000
Total RAM Bits	73728
Number of I/O	188
Number of Gates	-
Voltage - Supply	1.14V ~ 1.26V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	256-BGA
Supplier Device Package	256-FPBGA (17x17)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lfxp6e-3fn256c

Figure 2-1. LatticeXP Top Level Block Diagram

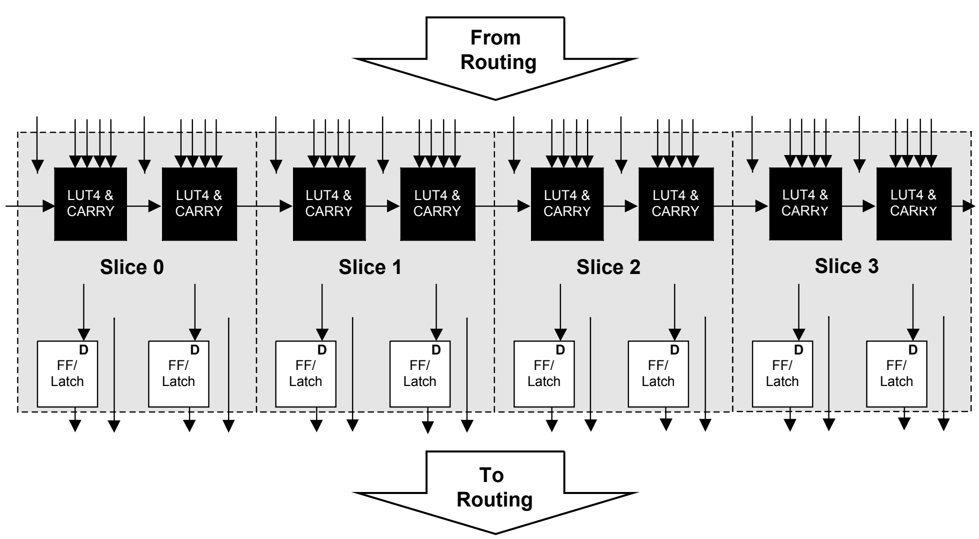


PFU and PFF Blocks

The core of the LatticeXP devices consists of PFU and PFF blocks. The PFUs can be programmed to perform Logic, Arithmetic, Distributed RAM and Distributed ROM functions. PFF blocks can be programmed to perform Logic, Arithmetic and ROM functions. Except where necessary, the remainder of the data sheet will use the term PFU to refer to both PFU and PFF blocks.

Each PFU block consists of four interconnected slices, numbered 0-3 as shown in Figure 2-2. All the interconnections to and from PFU blocks are from routing. There are 53 inputs and 25 outputs associated with each PFU block.

Figure 2-2. PFU Diagram



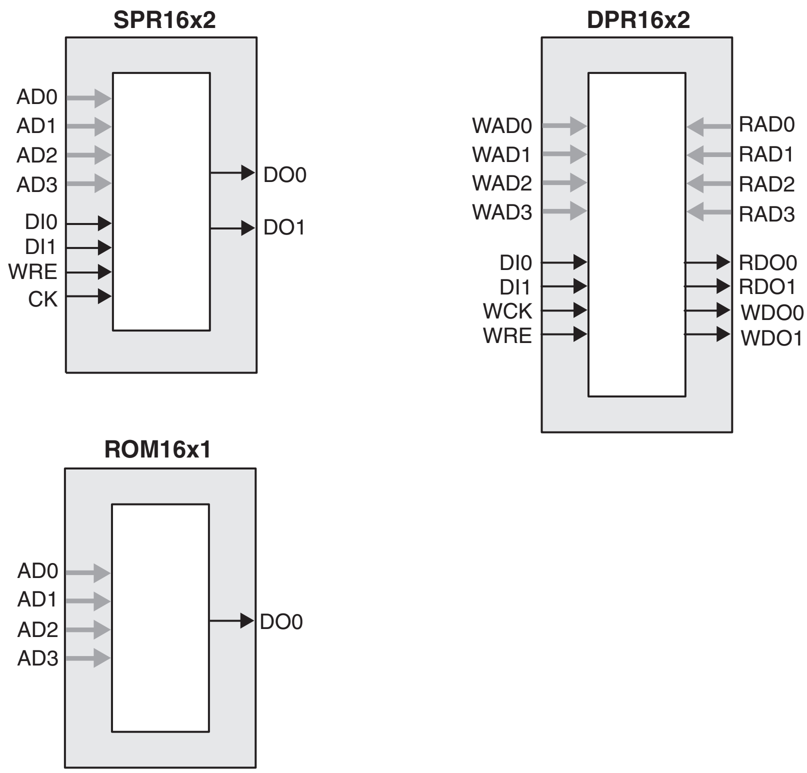
The Lattice design tools support the creation of a variety of different size memories. Where appropriate, the software will construct these using distributed memory primitives that represent the capabilities of the PFU. Table 2-3 shows the number of Slices required to implement different distributed RAM primitives. Figure 2-4 shows the distributed memory primitive block diagrams. Dual port memories involve the pairing of two Slices, one Slice functions as the read-write port. The other companion Slice supports the read-only port. For more information on RAM mode in LatticeXP devices, please see details of additional technical documentation at the end of this data sheet.

Table 2-3. Number of Slices Required for Implementing Distributed RAM

	SPR16x2	DPR16x2
Number of Slices	1	2

Note: SPR = Single Port RAM, DPR = Dual Port RAM

Figure 2-4. Distributed Memory Primitives



ROM Mode: The ROM mode uses the same principal as the RAM modes, but without the Write port. Pre-loading is accomplished through the programming interface during configuration.

PFU Modes of Operation

Slices can be combined within a PFU to form larger functions. Table 2-4 tabulates these modes and documents the functionality possible at the PFU level.

Figure 2-10. PLL Diagram

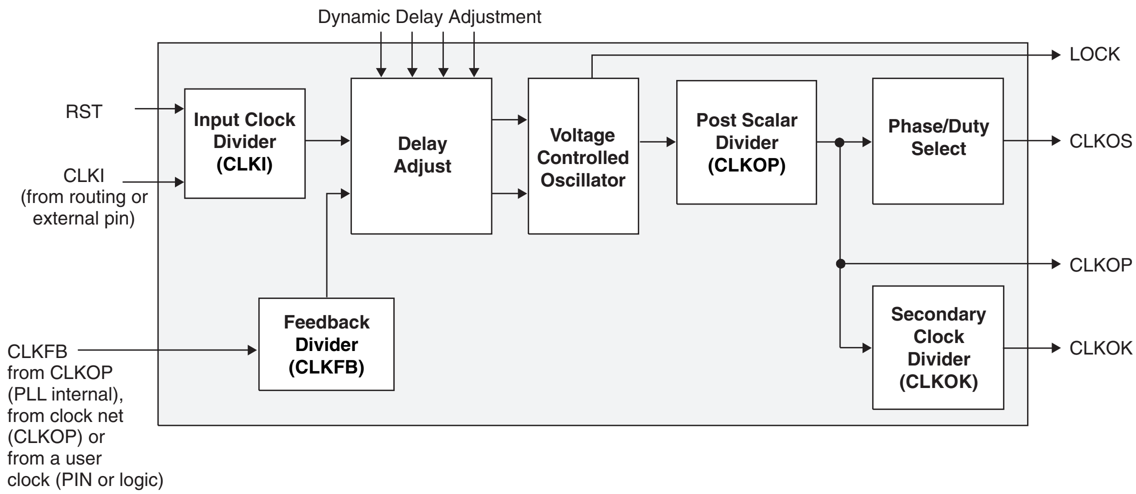


Figure 2-11 shows the available macros for the PLL. Table 2-11 provides signal description of the PLL Block.

Figure 2-11. PLL Primitive

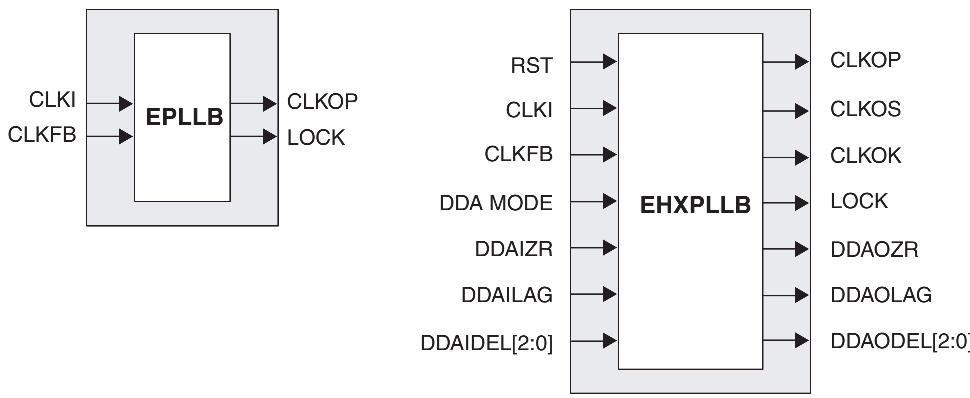
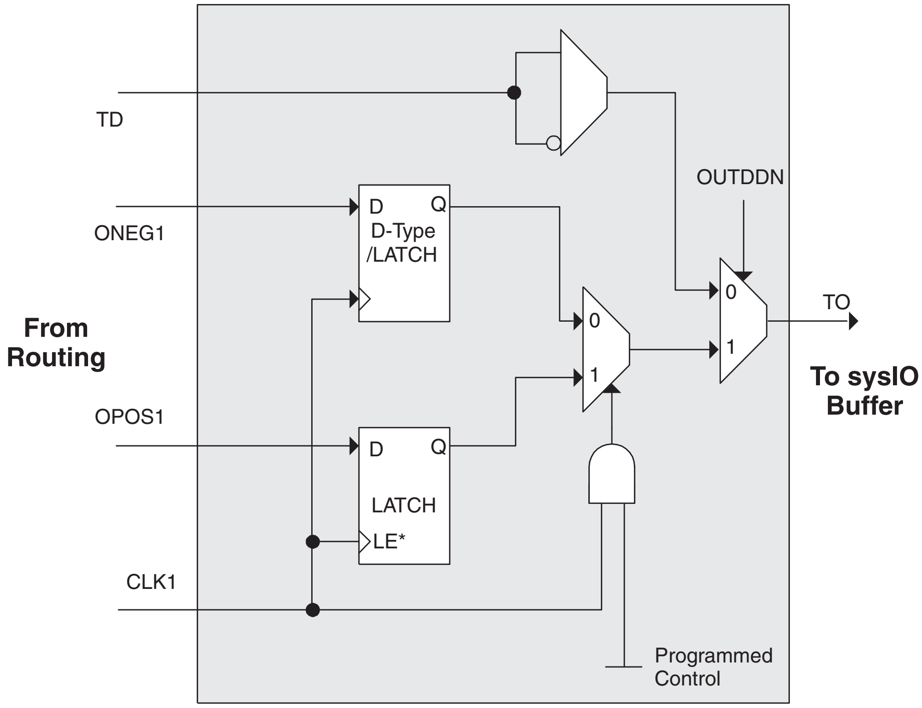


Table 2-5. PLL Signal Descriptions

Signal	I/O	Description
CLKI	I	Clock input from external pin or routing
CLKFB	I	PLL feedback input from CLKOP (PLL internal), from clock net (CLKOP) or from a user clock (PIN or logic)
RST	I	“1” to reset input clock divider
CLKOS	O	PLL output clock to clock tree (phase shifted/duty cycle changed)
CLKOP	O	PLL output clock to clock tree (No phase shift)
CLKOK	O	PLL output to clock tree through secondary clock divider
LOCK	O	“1” indicates PLL LOCK to CLKI
DDAMODE	I	Dynamic Delay Enable. “1” Pin control (dynamic), “0”: Fuse Control (static)
DDAIZR	I	Dynamic Delay Zero. “1”: delay = 0, “0”: delay = on
DDAILAG	I	Dynamic Delay Lag/Lead. “1”: Lag, “0”: Lead
DDAIDEL[2:0]	I	Dynamic Delay Input
DDAOZR	O	Dynamic Delay Zero Output
DDAOLAG	O	Dynamic Delay Lag/Lead Output
DDAODEL[2:0]	O	Dynamic Delay Output

Figure 2-25. Tristate Register Block



*Latch is transparent when input is low.

Control Logic Block

The control logic block allows the selection and modification of control signals for use in the PIO block. A clock is selected from one of the clock signals provided from the general purpose routing and a DQS signal provided from the programmable DQS pin. The clock can optionally be inverted.

The clock enable and local reset signals are selected from the routing and optionally inverted. The global tristate signal is passed through this block.

DDR Memory Support

Implementing high performance DDR memory interfaces requires dedicated DDR register structures in the input (for read operations) and in the output (for write operations). As indicated in the PIO Logic section, the LatticeXP devices provide this capability. In addition to these registers, the LatticeXP devices contain two elements to simplify the design of input structures for read operations: the DQS delay block and polarity control logic.

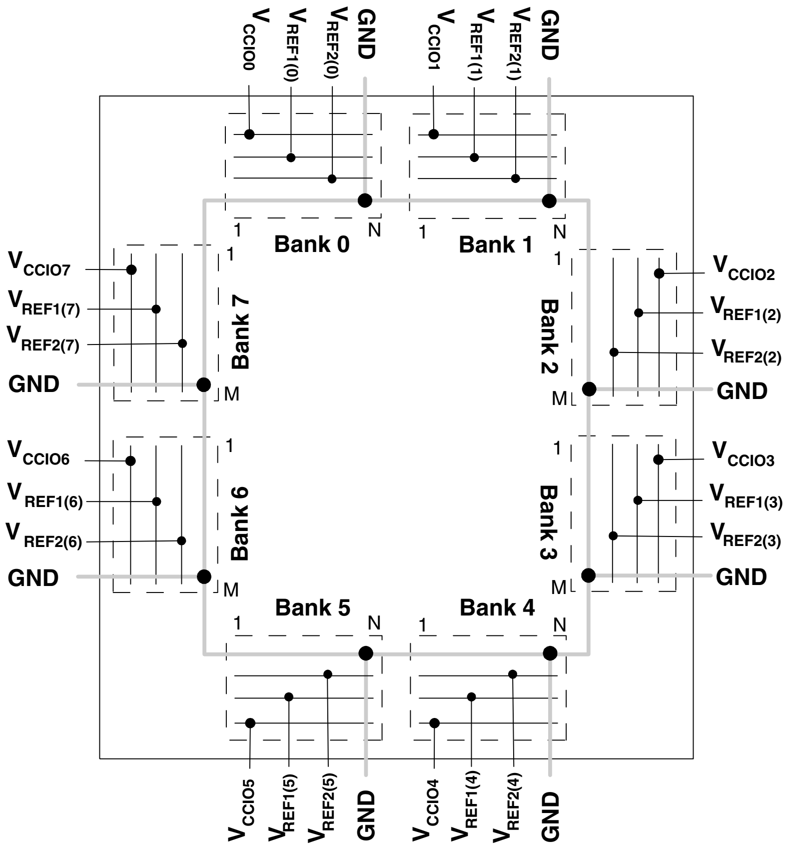
DLL Calibrated DQS Delay Block

Source Synchronous interfaces generally require the input clock to be adjusted in order to correctly capture data at the input register. For most interfaces a PLL is used for this adjustment, however in DDR memories the clock (referred to as DQS) is not free running so this approach cannot be used. The DQS Delay block provides the required clock alignment for DDR memory interfaces.

The DQS signal (selected PIOs only) feeds from the PAD through a DQS delay element to a dedicated DQS routing resource. The DQS signal also feeds the polarity control logic which controls the polarity of the clock to the sync registers in the input register blocks. Figures 2-26 and 2-27 show how the polarity control logic are routed to the PIOs.

The temperature, voltage and process variations of the DQS delay block are compensated by a set of calibration (6-bit bus) signals from two DLLs on opposite sides of the device. Each DLL compensates DQS Delays in its half of the device as shown in Figure 2-27. The DLL loop is compensated for temperature, voltage and process variations by the system clock and feedback loop.

Figure 2-28. LatticeXP Banks



Note: N and M are the maximum number of I/Os per bank.

LatticeXP devices contain two types of sysIO buffer pairs.

1. **Top and Bottom sysIO Buffer Pair (Single-Ended Outputs Only)**
   The sysIO buffer pairs in the top and bottom banks of the device consist of two single-ended output drivers and two sets of single-ended input buffers (both ratioed and referenced). The referenced input buffer can also be configured as a differential input.

   The two pads in the pair are described as “true” and “comp”, where the true pad is associated with the positive side of the differential input buffer and the comp (complementary) pad is associated with the negative side of the differential input buffer.

   Only the I/Os on the top and bottom banks have PCI clamps. Note that the PCI clamp is enabled after V_{CC}, V_{CCAUX} and V_{CCIO} are at valid operating levels and the device has been configured.

2. **Left and Right sysIO Buffer Pair (Differential and Single-Ended Outputs)**
   The sysIO buffer pairs in the left and right banks of the device consist of two single-ended output drivers, two sets of single-ended input buffers (both ratioed and referenced) and one differential output driver. The referenced input buffer can also be configured as a differential input. In these banks the two pads in the pair are described as “true” and “comp”, where the true pad is associated with the positive side of the differential I/O, and the comp (complementary) pad is associated with the negative side of the differential I/O.

   Select I/Os in the left and right banks have LVDS differential output drivers. Refer to the Logic Signal Connections tables for more information.

Typical I/O Behavior During Power-up

The internal power-on-reset (POR) signal is deactivated when V_{CC} and V_{CCAUX} have reached satisfactory levels. After the POR signal is deactivated, the FPGA core logic becomes active. It is the user's responsibility to ensure that all other V_{CCIO} banks are active with valid input logic levels to properly control the output logic states of all the I/O banks that are critical to the application. The default configuration of the I/O pins in a blank device is tri-state with a weak pull-up to VCCIO. The I/O pins will not take on the user configuration until VCC, VCCAUX and VCCIO have reached satisfactory levels at which time the I/Os will take on the user-configured settings.

The V_{CC} and V_{CCAUX} supply the power to the FPGA core fabric, whereas the V_{CCIO} supplies power to the I/O buffers. In order to simplify system design while providing consistent and predictable I/O behavior, it is recommended that the I/O buffers be powered-up prior to the FPGA core fabric. V_{CCIO} supplies should be powered up before or together with the V_{CC} and V_{CCAUX} supplies.

Supported Standards

The LatticeXP sysIO buffer supports both single-ended and differential standards. Single-ended standards can be further subdivided into LVCMOS, LVTTL and other standards. The buffers support the LVTTL, LVCMOS 1.2, 1.5, 1.8, 2.5 and 3.3V standards. In the LVCMOS and LVTTL modes, the buffer has individually configurable options for drive strength, bus maintenance (weak pull-up, weak pull-down, or a bus-keeper latch) and open drain. Other single-ended standards supported include SSTL and HSTL. Differential standards supported include LVDS, BLVDS, LVPECL, differential SSTL and differential HSTL. Tables 2-7 and 2-8 show the I/O standards (together with their supply and reference voltages) supported by the LatticeXP devices. For further information on utilizing the sysIO buffer to support a variety of standards please see the details of additional technical documentation at the end of this data sheet.

Table 2-7. Supported Input Standards

Input Standard	V_{REF} (Nom.)	V_{CCIO}[1] (Nom.)
Single Ended Interfaces		
LVTTL	—	—
LVCMOS33[2]	—	—
LVCMOS25[2]	—	—
LVCMOS18	—	1.8
LVCMOS15	—	1.5
LVCMOS12[2]	—	—
PCI	—	3.3
HSTL18 Class I, II	0.9	—
HSTL18 Class III	1.08	—
HSTL15 Class I	0.75	—
HSTL15 Class III	0.9	—
SSTL3 Class I, II	1.5	—
SSTL2 Class I, II	1.25	—
SSTL18 Class I	0.9	—
Differential Interfaces		
Differential SSTL18 Class I	—	—
Differential SSTL2 Class I, II	—	—
Differential SSTL3 Class I, II	—	—
Differential HSTL15 Class I, III	—	—
Differential HSTL18 Class I, II, III	—	—
LVDS, LVPECL	—	—
BLVDS	—	—

1. When not specified V_{CCIO} can be set anywhere in the valid operating range.
2. JTAG inputs do not have a fixed threshold option and always follow V_{CCJ}.

Table 2-8. Supported Output Standards

Output Standard	Drive	V_{CCIO} (Nom.)
Single-ended Interfaces		
LVTTL	4mA, 8mA, 12mA, 16mA, 20mA	3.3
LVCMOS33	4mA, 8mA, 12mA 16mA, 20mA	3.3
LVCMOS25	4mA, 8mA, 12mA 16mA, 20mA	2.5
LVCMOS18	4mA, 8mA, 12mA 16mA	1.8
LVCMOS15	4mA, 8mA	1.5
LVCMOS12	2mA, 6mA	1.2
LVCMOS33, Open Drain	4mA, 8mA, 12mA 16mA, 20mA	—
LVCMOS25, Open Drain	4mA, 8mA, 12mA 16mA, 20mA	—
LVCMOS18, Open Drain	4mA, 8mA, 12mA 16mA	—
LVCMOS15, Open Drain	4mA, 8mA	—
LVCMOS12, Open Drain	2mA. 6mA	—
PCI33	N/A	3.3
HSTL18 Class I, II, III	N/A	1.8
HSTL15 Class I, III	N/A	1.5
SSTL3 Class I, II	N/A	3.3
SSTL2 Class I, II	N/A	2.5
SSTL18 Class I	N/A	1.8
Differential Interfaces		
Differential SSTL3, Class I, II	N/A	3.3
Differential SSTL2, Class I, II	N/A	2.5
Differential SSTL18, Class I	N/A	1.8
Differential HSTL18, Class I, II, III	N/A	1.8
Differential HSTL15, Class I, III	N/A	1.5
LVDS	N/A	2.5
BLVDS[1]	N/A	2.5
LVPECL[1]	N/A	3.3

1. Emulated with external resistors.

Hot Socketing

The LatticeXP devices have been carefully designed to ensure predictable behavior during power-up and power-down. Power supplies can be sequenced in any order. During power up and power-down sequences, the I/Os remain in tristate until the power supply voltage is high enough to ensure reliable operation. In addition, leakage into I/O pins is controlled to within specified limits, which allows easy integration with the rest of the system. These capabilities make the LatticeXP ideal for many multiple power supply and hot-swap applications.

Sleep Mode

The LatticeXP “C” devices (V_{CC} = 1.8/2.5/3.3V) have a sleep mode that allows standby current to be reduced by up to three orders of magnitude during periods of system inactivity. Entry and exit to Sleep Mode is controlled by the SLEEPN pin.

During Sleep Mode, the FPGA logic is non-operational, registers and EBR contents are not maintained and I/Os are tri-stated. Do not enter Sleep Mode during device programming or configuration operation. In Sleep Mode, power supplies can be maintained in their normal operating range, eliminating the need for external switching of power supplies. Table 2-9 compares the characteristics of Normal, Off and Sleep Modes.

master serial clock is 2.5MHz. Table 2-10 lists all the available Master Serial Clock frequencies. When a different Master Serial Clock is selected during the design process, the following sequence takes place:

1. User selects a different Master Serial Clock frequency for configuration.
2. During configuration the device starts with the default (2.5MHz) Master Serial Clock frequency.
3. The clock configuration settings are contained in the early configuration bit stream.
4. The Master Serial Clock frequency changes to the selected frequency once the clock configuration bits are received.

For further information on the use of this oscillator for configuration, please see details of additional technical documentation at the end of this data sheet.

Table 2-10. Selectable Master Serial Clock (CCLK) Frequencies During Configuration

CCLK (MHz)	CCLK (MHz)	CCLK (MHz)
2.5[1]	13	45
4.3	15	51
5.4	20	55
6.9	26	60
8.1	30	130
9.2	34	—
10.0	41	—

1. Default

Density Shifting

The LatticeXP family has been designed to ensure that different density devices in the same package have the same pin-out. Furthermore, the architecture ensures a high success rate when performing design migration from lower density parts to higher density parts. In many cases, it is also possible to shift a lower utilization design targeted for a high-density device to a lower density device. However, the exact details of the final resource utilization will impact the likely success in each case.

Supply Current (Standby)[1, 2, 3, 4]

Over Recommended Operating Conditions

Symbol	Parameter	Device	Typ.[5]	Units
I_{CC}	Core Power Supply	LFXP3E	15	mA
		LFXP6E	20	mA
		LFXP10E	35	mA
		LFXP15E	45	mA
		LFXP20E	55	mA
		LFXP3C	35	mA
		LFXP6C	40	mA
		LFXP10C	70	mA
		LFXP15C	80	mA
		LFXP20C	90	mA
I_{CCP}	PLL Power Supply (per PLL)	All	8	mA
I_{CCAUX}	Auxiliary Power Supply V_{CCAUX} = 3.3V	LFXP3E/C	22	mA
		LFXP6E/C	22	mA
		LFXP10E/C	30	mA
		LFXP15E/C	30	mA
		LFXP20E/C	30	mA
I_{CCIO}	Bank Power Supply[6]	All	2	mA
I_{CCJ}	V_{CCJ} Power Supply	All	1	mA

1. For further information on supply current, please see details of additional technical documentation at the end of this data sheet.
2. Assumes all outputs are tristated, all inputs are configured as LVCMOS and held at the VCCIO or GND.
3. Frequency 0MHz.
4. User pattern: blank.
5. T_A=25°C, power supplies at nominal voltage.
6. Per bank.

Initialization Supply Current[1, 2, 3, 4, 5, 6]

Over Recommended Operating Conditions

Symbol	Parameter	Device	Typ.[7]	Units
I_{CC}	Core Power Supply	LFXP3E	40	mA
		LFXP6E	50	mA
		LFXP10E	110	mA
		LFXP15E	140	mA
		LFXP20E	250	mA
		LFXP3C	60	mA
		LFXP6C	70	mA
		LFXP10C	150	mA
		LFXP15C	180	mA
		LFXP20C	290	mA
I_{CCAUX}	Auxiliary Power Supply V_{CCAUX} = 3.3V	LFXP3E/C	50	mA
		LFXP6E/C	60	mA
		LFXP10E/C	90	mA
		LFXP15 /C	110	mA
		LFXP20E/C	130	mA
I_{CCJ}	V_{CCJ} Power Supply	All	2	mA

1. Until DONE signal is active.
2. For further information on supply current, please see details of additional technical documentation at the end of this data sheet.
3. Assumes all outputs are tristated, all inputs are configured as LVCMOS and held at the V_{CCIO} or GND.
4. Frequency 0MHz.
5. Typical user pattern.
6. Assume normal bypass capacitor/decoupling capacitor across the supply.
7. T_A=25°C, power supplies at nominal voltage.

Programming and Erase Flash Supply Current[1, 2, 3, 4, 5]

Symbol	Parameter	Device	Typ.[6]	Units
I_{CC}	Core Power Supply	LFXP3E	30	mA
		LFXP6E	40	mA
		LFXP10E	50	mA
		LFXP15E	60	mA
		LFXP20E	70	mA
		LFXP3C	50	mA
		LFXP6C	60	mA
		LFXP10C	90	mA
		LFXP15C	100	mA
		LFXP20C	110	mA
I_{CCAUX}	Auxiliary Power Supply V_{CCAUX} = 3.3V	LFXP3E/C	50	mA
		LFXP6E/C	60	mA
		LFXP10E/C	90	mA
		LFXP15E/C	110	mA
		LFXP20E/C	130	mA
I_{CCJ}	V_{CCJ} Power Supply[7]	All	2	mA

1. For further information on supply current, please see details of additional technical documentation at the end of this data sheet.
2. Assumes all outputs are tristated, all inputs are configured as LVCMOS and held at the V_{CCIO} or GND.
3. Blank user pattern; typical Flash pattern.
4. Bypass or decoupling capacitor across the supply.
5. JTAG programming is at 1MHz.
6. T_A=25°C, power supplies at nominal voltage.
7. When programming via JTAG.

LFXP3 Logic Signal Connections: 100 TQFP (Cont.)

Pin Number	Pin Function	Bank	Differential	Dual Function
44	GNDIO4	4	-	-
45	PB15A	4	T	PCLKT4_0
46	PB15B	4	C	PCLKC4_0
47	VCCIO4	4	-	-
48	PB19A	4	T	DQS
49	PB19B	4	C	VREF1_4
50	PB24A	4	-	VREF2_4
51	PR18B	3	C[3]	-
52	GNDIO3	3	-	-
53	PR18A	3	T[3]	-
54	PR15B	3	-	VREF1_3
55	PR14A	3	-	VREF2_3
56	PR13B	3	C	-
57	PR13A	3	T	-
58	VCCIO3	3	-	-
59	GNDP1	-	-	-
60	VCCP1	-	-	-
61	PR9B	2	C	PCLKC2_0
62	PR9A	2	T	PCLKT2_0
63	PR8B	2	C	RUM0_PLLC_IN_A
64	PR8A	2	T	RUM0_PLLT_IN_A
65	VCCIO2	2	-	-
66	PR6B	2	-	VREF1_2
67	PR5A	2	-	VREF2_2
68	GNDIO2	2	-	-
69	PR3B	2	C	RUM0_PLLC_FB_A
70	PR3A	2	T	RUM0_PLLT_FB_A
71	VCCAUX	-	-	-
72	TDO	-	-	-
73	VCCJ	-	-	-
74	TDI	-	-	-
75	TMS	-	-	-
76	TCK	-	-	-
77	VCC	-	-	-
78	PT24A	1	-	-
79	PT23A	1	-	D0
80	PT22B	1	-	D1
81	PT21A	1	-	D2
82	VCCIO1	1	-	-
83	PT20B	1	-	D3
84	GNDIO1	1	-	-
85	PT17A	1	-	D4
86	PT16A	1	-	D5
87	PT15B	1	-	D6

LFXP10, LFXP15 & LFXP20 Logic Signal Connections: 388 fpBGA (Cont.)

	LFXP10				LFXP15				LFXP20			
Ball Number	Ball Function	Bank	Diff.	Dual Function	Ball Function	Bank	Diff.	Dual Function	Ball Function	Bank	Diff.	Dual Function
M21	VCCP1	-	-	-	VCCP1	-	-	-	VCCP1	-	-	-
-	GNDIO2	2	-	-	GNDIO2	2	-	-	GNDIO2	2	-	-
M22	PR18B	2	C[3]	-	PR22B	2	C[3]	-	PR22B	2	C[3]	-
L22	PR18A	2	T[3]	-	PR22A	2	T[3]	-	PR22A	2	T[3]	-
K22	PR17B	2	C	PCLKC2_0	PR21B	2	C	PCLKC2_0	PR21B	2	C	PCLKC2_0
K21	PR17A	2	T	PCLKT2_0	PR21A	2	T	PCLKT2_0	PR21A	2	T	PCLKT2_0
L19	PR16B	2	C[3]	-	PR20B	2	C[3]	-	PR20B	2	C[3]	-
K20	PR16A	2	T[3]	DQS	PR20A	2	T[3]	DQS	PR20A	2	T[3]	DQS
L20	PR15B	2	-	-	PR19B	2	-	-	PR19B	2	-	-
L21	PR14A	2	-	VREF1_2	PR18A	2	-	VREF1_2	PR18A	2	-	VREF1_2
-	GNDIO2	2	-	-	GNDIO2	2	-	-	GNDIO2	2	-	-
J22	PR13B	2	C[3]	-	PR17B	2	C[3]	-	PR17B	2	C[3]	-
J21	PR13A	2	T[3]	-	PR17A	2	T[3]	-	PR17A	2	T[3]	-
H22	PR12B	2	C	RUM0_PLLC_IN_A	PR16B	2	C	RUM0_PLLC_IN_A	PR16B	2	C	RUM0_PLLC_IN_A
H21	PR12A	2	T	RUM0_PLLT_IN_A	PR16A	2	T	RUM0_PLLT_IN_A	PR16A	2	T	RUM0_PLLT_IN_A
K19	PR11B	2	C[3]	-	PR15B	2	C[3]	-	PR15B	2	C[3]	-
J19	PR11A	2	T[3]	-	PR15A	2	T[3]	-	PR15A	2	T[3]	-
-	GNDIO2	2	-	-	GNDIO2	2	-	-	GNDIO2	2	-	-
J20	PR9B	2	C[3]	-	PR13B	2	C[3]	-	PR13B	2	C[3]	-
H20	PR9A	2	T[3]	-	PR13A	2	T[3]	-	PR13A	2	T[3]	-
H19	PR8B	2	C	-	PR12B	2	C	-	PR12B	2	C	-
G19	PR8A	2	T	-	PR12A	2	T	-	PR12A	2	T	-
G22	PR7B	2	C[3]	-	PR11B	2	C[3]	-	PR11B	2	C[3]	-
G21	PR7A	2	T[3]	DQS	PR11A	2	T[3]	DQS	PR11A	2	T[3]	DQS
-	GNDIO2	2	-	-	GNDIO2	2	-	-	GNDIO2	2	-	-
F20	PR6B	2	-	-	PR10B	2	-	-	PR10B	2	-	-
G20	PR5A	2	-	VREF2_2	PR9A	2	-	VREF2_2	PR9A	2	-	VREF2_2
F22	PR4B	2	C[3]	-	PR8B	2	C[3]	-	PR8B	2	C[3]	-
F21	PR4A	2	T[3]	-	PR8A	2	T[3]	-	PR8A	2	T[3]	-
E22	PR3B	2	C	RUM0_PLLC_FB_A	PR7B	2	C	RUM0_PLLC_FB_A	PR7B	2	C	RUM0_PLLC_FB_A
E21	PR3A	2	T	RUM0_PLLT_FB_A	PR7A	2	T	RUM0_PLLT_FB_A	PR7A	2	T	RUM0_PLLT_FB_A
D22	PR2B	2	C[3]	-	PR6B	2	C[3]	-	PR6B	2	C[3]	-
D21	PR2A	2	T[3]	-	PR6A	2	T[3]	-	PR6A	2	T[3]	-
-	GNDIO2	2	-	-	GNDIO2	2	-	-	GNDIO2	2	-	-
F19	TDO	-	-	-	TDO	-	-	-	TDO	-	-	-
E20	VCCJ	-	-	-	VCCJ	-	-	-	VCCJ	-	-	-
D20	TDI	-	-	-	TDI	-	-	-	TDI	-	-	-
D19	TMS	-	-	-	TMS	-	-	-	TMS	-	-	-
D18	TCK	-	-	-	TCK	-	-	-	TCK	-	-	-
-	GNDIO1	1	-	-	GNDIO1	1	-	-	GNDIO1	1	-	-
E19	-	-	-	-	PT48A	1	-	-	PT52A	1	-	-
D17	-	-	-	-	PT47B	1	C	-	PT51B	1	C	-
D16	-	-	-	-	PT47A	1	T	DQS	PT51A	1	T	DQS
C16	-	-	-	-	PT46B	1	-	-	PT50B	1	-	-
C15	-	-	-	-	PT45A	1	-	-	PT49A	1	-	-
C17	-	-	-	-	PT44B	1	C	-	PT48B	1	C	-
C18	PT39A	1	-	-	PT44A	1	T	-	PT48A	1	T	-
C19	PT38B	1	C	-	PT43B	1	C	-	PT47B	1	C	-
-	GNDIO1	1	-	-	GNDIO1	1	-	-	GNDIO1	1	-	-

LFXP10, LFXP15 & LFXP20 Logic Signal Connections: 388 fpBGA (Cont.)

	LFXP10				LFXP15				LFXP20			
Ball Number	Ball Function	Bank	Diff.	Dual Function	Ball Function	Bank	Diff.	Dual Function	Ball Function	Bank	Diff.	Dual Function
K11	GND	-	-	-	GND	-	-	-	GND	-	-	-
K12	GND	-	-	-	GND	-	-	-	GND	-	-	-
K13	GND	-	-	-	GND	-	-	-	GND	-	-	-
K14	GND	-	-	-	GND	-	-	-	GND	-	-	-
K9	GND	-	-	-	GND	-	-	-	GND	-	-	-
L10	GND	-	-	-	GND	-	-	-	GND	-	-	-
L11	GND	-	-	-	GND	-	-	-	GND	-	-	-
L12	GND	-	-	-	GND	-	-	-	GND	-	-	-
L13	GND	-	-	-	GND	-	-	-	GND	-	-	-
L14	GND	-	-	-	GND	-	-	-	GND	-	-	-
L9	GND	-	-	-	GND	-	-	-	GND	-	-	-
M10	GND	-	-	-	GND	-	-	-	GND	-	-	-
M11	GND	-	-	-	GND	-	-	-	GND	-	-	-
M12	GND	-	-	-	GND	-	-	-	GND	-	-	-
M13	GND	-	-	-	GND	-	-	-	GND	-	-	-
M14	GND	-	-	-	GND	-	-	-	GND	-	-	-
M9	GND	-	-	-	GND	-	-	-	GND	-	-	-
N10	GND	-	-	-	GND	-	-	-	GND	-	-	-
N11	GND	-	-	-	GND	-	-	-	GND	-	-	-
N12	GND	-	-	-	GND	-	-	-	GND	-	-	-
N13	GND	-	-	-	GND	-	-	-	GND	-	-	-
N14	GND	-	-	-	GND	-	-	-	GND	-	-	-
N9	GND	-	-	-	GND	-	-	-	GND	-	-	-
P10	GND	-	-	-	GND	-	-	-	GND	-	-	-
P11	GND	-	-	-	GND	-	-	-	GND	-	-	-
P12	GND	-	-	-	GND	-	-	-	GND	-	-	-
P13	GND	-	-	-	GND	-	-	-	GND	-	-	-
P14	GND	-	-	-	GND	-	-	-	GND	-	-	-
P9	GND	-	-	-	GND	-	-	-	GND	-	-	-
R10	GND	-	-	-	GND	-	-	-	GND	-	-	-
R11	GND	-	-	-	GND	-	-	-	GND	-	-	-
R12	GND	-	-	-	GND	-	-	-	GND	-	-	-
R13	GND	-	-	-	GND	-	-	-	GND	-	-	-
R14	GND	-	-	-	GND	-	-	-	GND	-	-	-
H9	VCC	-	-	-	VCC	-	-	-	VCC	-	-	-
J15	VCC	-	-	-	VCC	-	-	-	VCC	-	-	-
J8	VCC	-	-	-	VCC	-	-	-	VCC	-	-	-
K15	VCC	-	-	-	VCC	-	-	-	VCC	-	-	-
K8	VCC	-	-	-	VCC	-	-	-	VCC	-	-	-
L15	VCC	-	-	-	VCC	-	-	-	VCC	-	-	-
L8	VCC	-	-	-	VCC	-	-	-	VCC	-	-	-
M15	VCC	-	-	-	VCC	-	-	-	VCC	-	-	-
M8	VCC	-	-	-	VCC	-	-	-	VCC	-	-	-
N15	VCC	-	-	-	VCC	-	-	-	VCC	-	-	-
N8	VCC	-	-	-	VCC	-	-	-	VCC	-	-	-
P15	VCC	-	-	-	VCC	-	-	-	VCC	-	-	-
P8	VCC	-	-	-	VCC	-	-	-	VCC	-	-	-
R9	VCC	-	-	-	VCC	-	-	-	VCC	-	-	-
G16	VCCAUX	-	-	-	VCCAUX	-	-	-	VCCAUX	-	-	-

LFXP15 & LFXP20 Logic Signal Connections: 484 fpBGA (Cont.)

Ball Number	LFXP15 Ball Function	LFXP15 Bank	LFXP15 Differential	LFXP15 Dual Function	LFXP20 Ball Function	LFXP20 Bank	LFXP20 Differential	LFXP20 Dual Function
L1	-	-	-	-	PL23A	7	T[3]	-
M1	-	-	-	-	PL23B	7	C[3]	-
M2	-	-	-	-	PL24A	7	-	-
L5	VCCP0	-	-	-	VCCP0	-	-	-
N2	GNDP0	-	-	-	GNDP0	-	-	-
N1	-	-	-	-	PL25B	6	-	-
P2	-	-	-	-	PL26A	6	T[3]	-
P1	-	-	-	-	PL26B	6	C[3]	-
M4	PL23A	6	T[3]	-	PL27A	6	T[3]	-
M3	PL23B	6	C[3]	-	PL27B	6	C[3]	-
R2	PL24A	6	T	PCLKT6_0	PL28A	6	T	PCLKT6_0
-	GNDIO6	6	-	-	GNDIO6	6	-	-
R1	PL24B	6	C	PCLKC6_0	PL28B	6	C	PCLKC6_0
N3	PL25A	6	T[3]	-	PL29A	6	T[3]	-
N4	PL25B	6	C[3]	-	PL29B	6	C[3]	-
M5	PL26A	6	-	-	PL30A	6	-	-
N5	PL27B	6	-	VREF1_6	PL31B	6	-	VREF1_6
T2	PL28A	6	T[3]	DQS	PL32A	6	T[3]	DQS
T1	PL28B	6	C[3]	-	PL32B	6	C[3]	-
-	GNDIO6	6	-	-	GNDIO6	6	-	-
U2	PL29A	6	T	LLM0_PLLT_IN_A	PL33A	6	T	LLM0_PLLT_IN_A
U1	PL29B	6	C	LLM0_PLLC_IN_A	PL33B	6	C	LLM0_PLLC_IN_A
P3	PL30A	6	T[3]	-	PL34A	6	T[3]	-
P4	PL30B	6	C[3]	-	PL34B	6	C[3]	-
P6	PL32A	6	T[3]	-	PL36A	6	T[3]	-
P5	PL32B	6	C[3]	-	PL36B	6	C[3]	-
-	GNDIO6	6	-	-	GNDIO6	6	-	-
V2	PL33A	6	T	-	PL37A	6	T	-
V1	PL33B	6	C	-	PL37B	6	C	-
W2	PL34A	6	T[3]	-	PL38A	6	T[3]	-
W1	PL34B	6	C[3]	-	PL38B	6	C[3]	-
R3	PL35A	6	-	VREF2_6	PL39A	6	-	VREF2_6
R4	PL36B	6	-	-	PL40B	6	-	-
R6	PL37A	6	T[3]	DQS	PL41A	6	T[3]	DQS
R5	PL37B	6	C[3]	-	PL41B	6	C[3]	-
-	GNDIO6	6	-	-	GNDIO6	6	-	-
Y2	PL38A	6	T	LLM0_PLLT_FB_A	PL42A	6	T	LLM0_PLLT_FB_A
Y1	PL38B	6	C	LLM0_PLLC_FB_A	PL42B	6	C	LLM0_PLLC_FB_A
T3	PL39A	6	T[3]	-	PL43A	6	T[3]	-
T4	PL39B	6	C[3]	-	PL43B	6	C[3]	-
W3	PL40A	6	T[3]	-	PL44A	6	T[3]	-
V3	PL40B	6	C[3]	-	PL44B	6	C[3]	-

LFXP15 & LFXP20 Logic Signal Connections: 484 fpBGA (Cont.)

	LFXP15				LFXP20			
Ball Number	Ball Function	Bank	Differential	Dual Function	Ball Function	Bank	Differential	Dual Function
A14	PT30B	1	-	-	PT34B	1	-	-
B14	PT29A	1	-	D4	PT33A	1	-	D4
C12	PT28B	1	C	-	PT32B	1	C	-
B12	PT28A	1	T	D5	PT32A	1	T	D5
-	GNDIO1	1	-	-	GNDIO1	1	-	-
D12	PT27B	1	C	D6	PT31B	1	C	D6
E12	PT27A	1	T	-	PT31A	1	T	-
A13	PT26B	1	C	D7	PT30B	1	C	D7
A12	PT26A	1	T	-	PT30A	1	T	-
A11	PT25B	0	C	BUSY	PT29B	0	C	BUSY
-	GNDIO0	0	-	-	GNDIO0	0	-	-
A10	PT25A	0	T	CS1N	PT29A	0	T	CS1N
D11	PT24B	0	C	PCLKC0_0	PT28B	0	C	PCLKC0_0
E11	PT24A	0	T	PCLKT0_0	PT28A	0	T	PCLKT0_0
B11	PT23B	0	C	-	PT27B	0	C	-
C11	PT23A	0	T	DQS	PT27A	0	T	DQS
B9	PT22B	0	-	-	PT26B	0	-	-
A9	PT21A	0	-	DOUT	PT25A	0	-	DOUT
B8	PT20B	0	C	-	PT24B	0	C	-
-	GNDIO0	0	-	-	GNDIO0	0	-	-
A8	PT20A	0	T	WRITEN	PT24A	0	T	WRITEN
E10	PT19B	0	C	-	PT23B	0	C	-
D10	PT19A	0	T	VREF1_0	PT23A	0	T	VREF1_0
C10	PT18B	0	C	-	PT22B	0	C	-
B10	PT18A	0	T	DI	PT22A	0	T	DI
B7	PT17B	0	C	-	PT21B	0	C	-
A7	PT17A	0	T	CSN	PT21A	0	T	CSN
C9	PT16B	0	C	-	PT20B	0	C	-
D9	PT16A	0	T	-	PT20A	0	T	-
B6	PT15B	0	C	VREF2_0	PT19B	0	C	VREF2_0
A6	PT15A	0	T	DQS	PT19A	0	T	DQS
F9	PT14B	0	-	-	PT18B	0	-	-
E9	PT13A	0	-	-	PT17A	0	-	-
-	GNDIO0	0	-	-	GNDIO0	0	-	-
B5	PT12B	0	C	-	PT16B	0	C	-
A5	PT12A	0	T	-	PT16A	0	T	-
C8	PT11B	0	C	-	PT15B	0	C	-
D8	PT11A	0	T	-	PT15A	0	T	-
B4	PT10B	0	C	-	PT14B	0	C	-
A4	PT10A	0	T	-	PT14A	0	T	-
F8	PT9B	0	C	-	PT13B	0	C	-
E8	PT9A	0	T	-	PT13A	0	T	-

LatticeXP Family Data Sheet
Ordering Information

December 2005 | Data Sheet DS1001

Part Number Description

LFXP XX X – X XXXXXX X

Device Family
LatticeXP FPGA

Logic Capacity
3K LUTs = 3
6K LUTs = 6
10K LUTs = 10
15K LUTs = 15
20K LUTs = 20

Supply Voltage
C = 1.8V/2.5V/3.3V
E = 1.2V

Note: Parts dual marked per table below.

Grade
C = Commercial
I = Industrial

Package
T100 = 100-pin TQFP
T144 = 144-pin TQFP
Q208 = 208-pin PQFP
F256 = 256-ball fpBGA
F388 = 388-ball fpBGA
F484 = 484-ball fpBGA

TN100 = 100-pin Lead-free TQFP
TN144 = 144-pin Lead-free TQFP
QN208 = 208-pin Lead-free PQFP
FN256 = 256-ball Lead-free fpBGA
FN388 = 388-ball Lead-free fpBGA
FN484 = 484-ball Lead-free fpBGA

Speed
3 = Slowest
4
5 = Fastest

Ordering Information (Contact Factory for Specific Device Availability)

Note:þLatticeXP devices are dual marked. For example, the commercial speed grade LFXP10E-4F256C is also marked with industrial grade -3I (LFXP10E-3F256I). The commercial grade is one speed grade faster than the associated dual mark industrial grade. The slowest commercial speed grade does not have industrial markings. The markings appear as follows:

Commercial (Cont.)

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP6E-3F256C	188	1.2V	-3	fpBGA	256	COM	5.8K
LFXP6E-4F256C	188	1.2V	-4	fpBGA	256	COM	5.8K
LFXP6E-5F256C	188	1.2V	-5	fpBGA	256	COM	5.8K
LFXP6E-3Q208C	142	1.2V	-3	PQFP	208	COM	5.8K
LFXP6E-4Q208C	142	1.2V	-4	PQFP	208	COM	5.8K
LFXP6E-5Q208C	142	1.2V	-5	PQFP	208	COM	5.8K
LFXP6E-3T144C	100	1.2V	-3	TQFP	144	COM	5.8K
LFXP6E-4T144C	100	1.2V	-4	TQFP	144	COM	5.8K
LFXP6E-5T144C	100	1.2V	-5	TQFP	144	COM	5.8K

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP10E-3F388C	244	1.2V	-3	fpBGA	388	COM	9.7K
LFXP10E-4F388C	244	1.2V	-4	fpBGA	388	COM	9.7K
LFXP10E-5F388C	244	1.2V	-5	fpBGA	388	COM	9.7K
LFXP10E-3F256C	188	1.2V	-3	fpBGA	256	COM	9.7K
LFXP10E-4F256C	188	1.2V	-4	fpBGA	256	COM	9.7K
LFXP10E-5F256C	188	1.2V	-5	fpBGA	256	COM	9.7K

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP15E-3F484C	300	1.2V	-3	fpBGA	484	COM	15.5K
LFXP15E-4F484C	300	1.2V	-4	fpBGA	484	COM	15.5K
LFXP15E-5F484C	300	1.2V	-5	fpBGA	484	COM	15.5K
LFXP15E-3F388C	268	1.2V	-3	fpBGA	388	COM	15.5K
LFXP15E-4F388C	268	1.2V	-4	fpBGA	388	COM	15.5K
LFXP15E-5F388C	268	1.2V	-5	fpBGA	388	COM	15.5K
LFXP15E-3F256C	188	1.2V	-3	fpBGA	256	COM	15.5K
LFXP15E-4F256C	188	1.2V	-4	fpBGA	256	COM	15.5K
LFXP15E-5F256C	188	1.2V	-5	fpBGA	256	COM	15.5K

Industrial (Cont.)

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP10E-3FN388I	244	1.2V	-3	fpBGA	388	IND	9.7K
LFXP10E-4FN388I	244	1.2V	-4	fpBGA	388	IND	9.7K
LFXP10E-3FN256I	188	1.2V	-3	fpBGA	256	IND	9.7K
LFXP10E-4FN256I	188	1.2V	-4	fpBGA	256	IND	9.7K

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP15E-3FN484I	300	1.2V	-3	fpBGA	484	IND	15.5K
LFXP15E-4FN484I	300	1.2V	-4	fpBGA	484	IND	15.5K
LFXP15E-3FN388I	268	1.2V	-3	fpBGA	388	IND	15.5K
LFXP15E-4FN388I	268	1.2V	-4	fpBGA	388	IND	15.5K
LFXP15E-3FN256I	188	1.2V	-3	fpBGA	256	IND	15.5K
LFXP15E-4FN256I	188	1.2V	-4	fpBGA	256	IND	15.5K

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP20E-3FN484I	340	1.2V	-3	fpBGA	484	IND	19.7K
LFXP20E-4FN484I	340	1.2V	-4	fpBGA	484	IND	19.7K
LFXP20E-3FN388I	268	1.2V	-3	fpBGA	388	IND	19.7K
LFXP20E-4FN388I	268	1.2V	-4	fpBGA	388	IND	19.7K
LFXP20E-3FN256I	188	1.2V	-3	fpBGA	256	IND	19.7K
LFXP20E-4FN256I	188	1.2V	-4	fpBGA	256	IND	19.7K

LatticeXP Family Data Sheet Revision History

Revision History

Date	Version	Section	Change Summary
February 2005	01.0	—	Initial release.
April 2005	01.1	Architecture	EBR memory support section updated with clarification.
May 2005	01.2	Introduction	Added TransFR Reconfiguration to Features section.
		Architecture	Added TransFR section.
June 2005	01.3	Pinout Information	Added pinout information for LFXP3, LFXP6, LFXP15 and LFXP20.
July 2005	02.0	Introduction	Updated XP6, XP15 and XP20 EBR SRAM Bits and Block numbers.
		Architecture	Updated Per Quadrant Primary Clock Selection figure.
			Added Typical I/O Behavior During Power-up section.
			Updated Device Configuration section under Configuration and Testing.
		DC and Switching Characteristics	Clarified Hot Socketing Specification
			Updated Supply Current (Standby) Table
			Updated Initialization Supply Current Table
			Added Programming and Erase Flash Supply Current table
			Added LVDS Emulation section. Updated LVDS25E Output Termination Example figure and LVDS25E DC Conditions table.
			Updated Differential LVPECL diagram and LVPECL DC Conditions table.
			Deleted 5V Tolerant Input Buffer section. Updated RSDS figure and RSDS DC Conditions table.
			Updated sysCONFIG Port Timing Specifications
			Updated JTAG Port Timing Specifications. Added Flash Download Time table.
		Pinout Information	Updated Signal Descriptions table.
			Updated Logic Signal Connections Dual Function column.
		Ordering Information	Added lead-free ordering part numbers.
July 2005	02.1	DC and Switching Characteristics	Clarification of Flash Programming Junction Temperature
August 2005	02.2	Introduction	Added Sleep Mode feature.
		Architecture	Added Sleep Mode section.
		DC and Switching Characteristics	Added Sleep Mode Supply Current Table
			Added Sleep Mode Timing section
		Pinout Information	Added SLEEPN and TOE signal names, descriptions and footnotes.
			Added SLEEPN and TOE to pinout information and footnotes.
			Added footnote 3 to Logic Signal Connections tables for clarification on emulated LVDS output.
September 2005	03.0	Architecture	Added clarification of PCI clamp.
			Added clarification to SLEEPN Pin Characteristics section.
		DC and Switching Characteristics	DC Characteristics, added footnote 4 for clarification. Updated Supply Current (Sleep Mode), Supply Current (Standby), Initialization Supply Current, and Programming and Erase Flash Supply Current typical numbers.